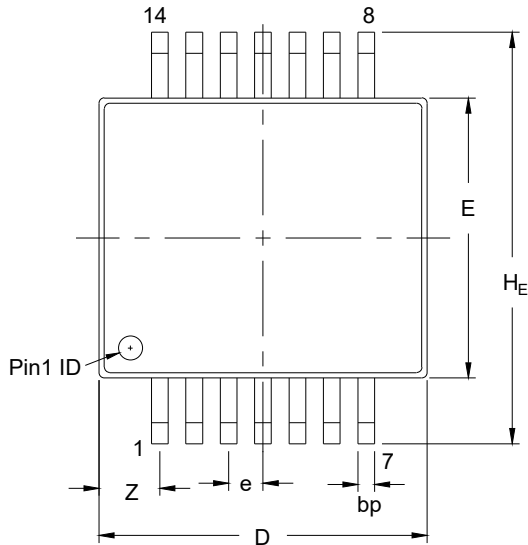
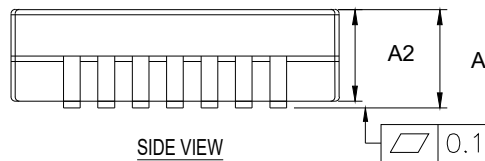


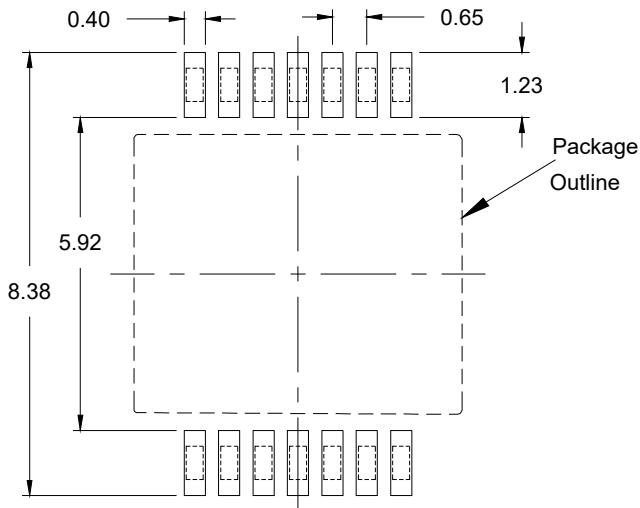
BASED ON JEDEC JEP95: MO-150



TOP VIEW



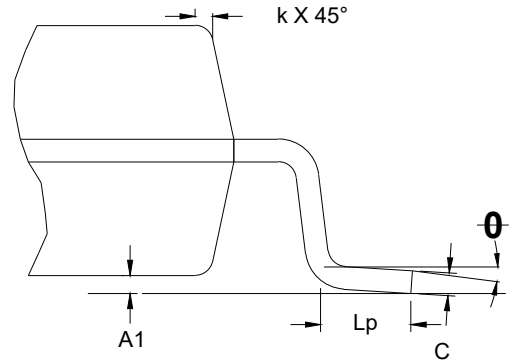
SIDE VIEW



RECOMMENDED LAND PATTERN  
(PCB Top View, SMD Design)

- 1. Dimensions
- 2. Weight  $\leq 0.3$  g
- 3. Body Material LOW STRESS EPOXY
- 4. Lead Material FeNi-ALLOY or Cu-ALLOY
- 5. Lead Finish SOLDER PLATING
- 6. Lead Form Z-BENDS

VIEW X



DIMENSIONS OF SUB-GROUP C1	
A min	1.73
A1 min	0.05
A1 max	0.21
A2 min	1.68
A2 max	1.78
c min	0.09
c max	0.20
D min*	6.07
D max*	6.33
E min*	5.20
E max*	5.38
k min	0.25
$\theta$ max	0°
$\theta$ max	10°

\* WITHOUT MOLD FLASH

DIMENSIONS OF SUB-GROUP B1	
A max	1.99
bp min	0.25
bp max	0.38
e nom	0.65
H <sub>E</sub> min	7.40
H <sub>E</sub> max	8.20
Lpmin	0.63
Z max	1.22

NOTES:

- 1. JEDEC compatible.
- 2. All dimensions are in mm and angles are in degrees.